

# **DATA SHEET**

**74LVC374**

**Octal D-type flip-flop;  
positive edge-trigger (3-State)**

Product specification  
Supersedes data of February 1996  
IC24 Data Handbook

1997 Mar 12

**Octal D-type flip-flop; positive edge-triggered (3-State)****74LVC374****FEATURES**

- Wide supply voltage range of 1.2V to 3.6V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 8-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Output drive capability 50Ω transmission lines @ 85°C

**DESCRIPTION**

The 74LVC374 is a high-performance low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC374 is an octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-State outputs for bus oriented applications. A clock (CP) and an output enable ( $\overline{OE}$ ) input are common to all flip-flops.

The eight flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition.

When  $\overline{OE}$  is LOW, the contents of the eight flip-flops is available at the outputs. When  $\overline{OE}$  is HIGH, the outputs go to the high impedance OFF-state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops. The '374' is functionally identical to the '574' but the '574' has a different pin arrangement.

**QUICK REFERENCE DATA**GND = 0V;  $T_{amb}$  = 25°C;  $t_r = t_f \leq 2.5$  ns

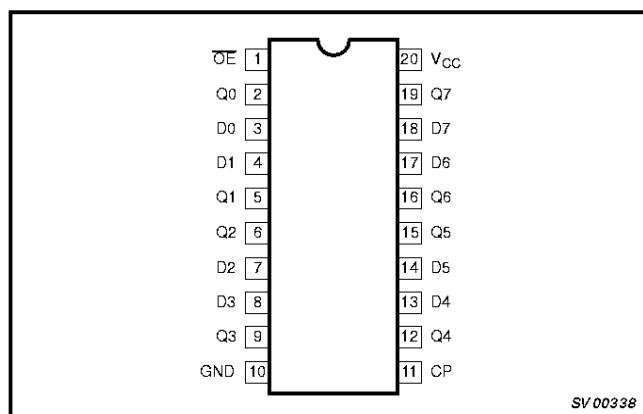
SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
$t_{PHL}/t_{PLH}$	Propagation delay CP to Qn	$C_L = 50\text{pF}$ $V_{CC} = 3.3\text{V}$	4.8	ns
$f_{max}$	Maximum clock frequency	$C_L = 50\text{pF}$ $V_{CC} = 3.3\text{V}$	150	MHz
$C_I$	Input capacitance		5.0	pF
$C_{PD}$	Power dissipation capacitance per flip-flop	Notes 1 and 2	28	pF

**NOTES:**

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ )
 
$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$$
 where:  
 $f_i$  = input frequency in MHz;  $C_L$  = output load capacity in pF;  
 $f_o$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;  
 $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.
2. The condition is  $V_I = \text{GND}$  to  $V_{CC}$

**ORDERING INFORMATION**

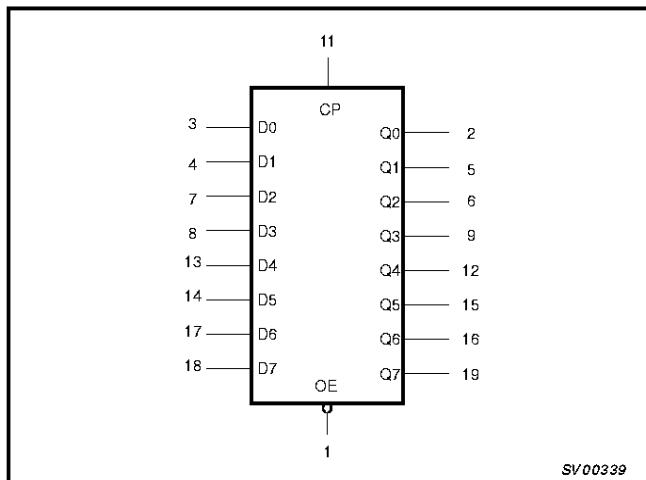
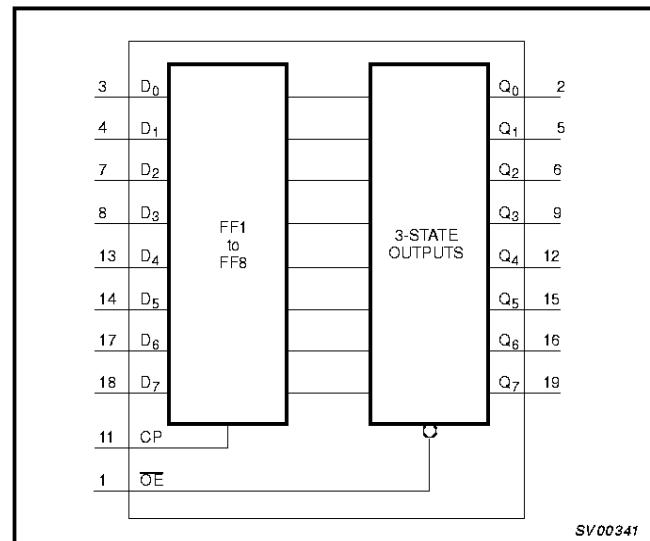
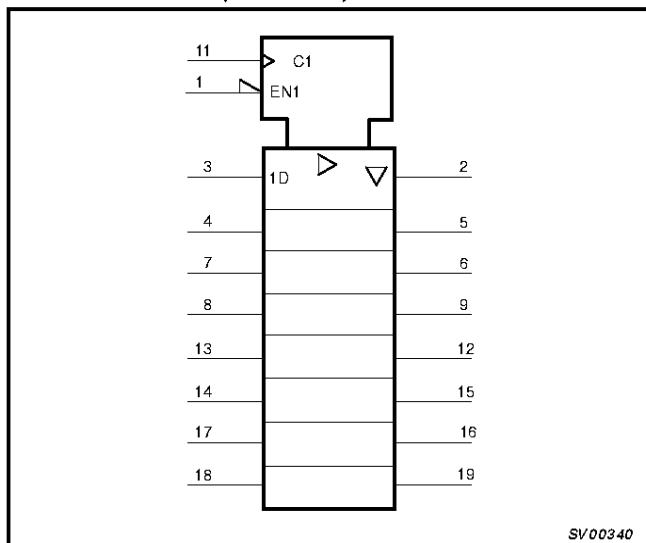
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic SO	-40°C to +85°C	74LVC374 D	74LVC374 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC374 DB	74LVC374 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC374 PW	74LVC374PW DH	SOT360-1

**PIN CONFIGURATION****PIN DESCRIPTION**

PIN NUMBER	SYMBOL	FUNCTION
1	$\overline{OE}$	Output enable input (active-LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q0 to Q7	3-State flip-flop outputs
3, 4, 7, 8, 13, 14, 17, 18	D0 to D7	Data inputs
10	GND	Ground (0V)
11	CP	Clock input (LOW-to-HIGH, edge-triggered)
20	$V_{CC}$	Positive supply voltage

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**LOGIC SYMBOL****FUNCTIONAL DIAGRAM****LOGIC SYMBOL (IEEE/IEC)****FUNCTION TABLE**

OPERATING MODES	INPUTS			INTERNAL FLIP-FLOPS	OUTPUTS Q0 to Q7
	OE	CP	Dn		
Load and read register	L	↑	I	L	L
Load register and disable outputs	H	↑	h	H	Z

H = HIGH voltage level

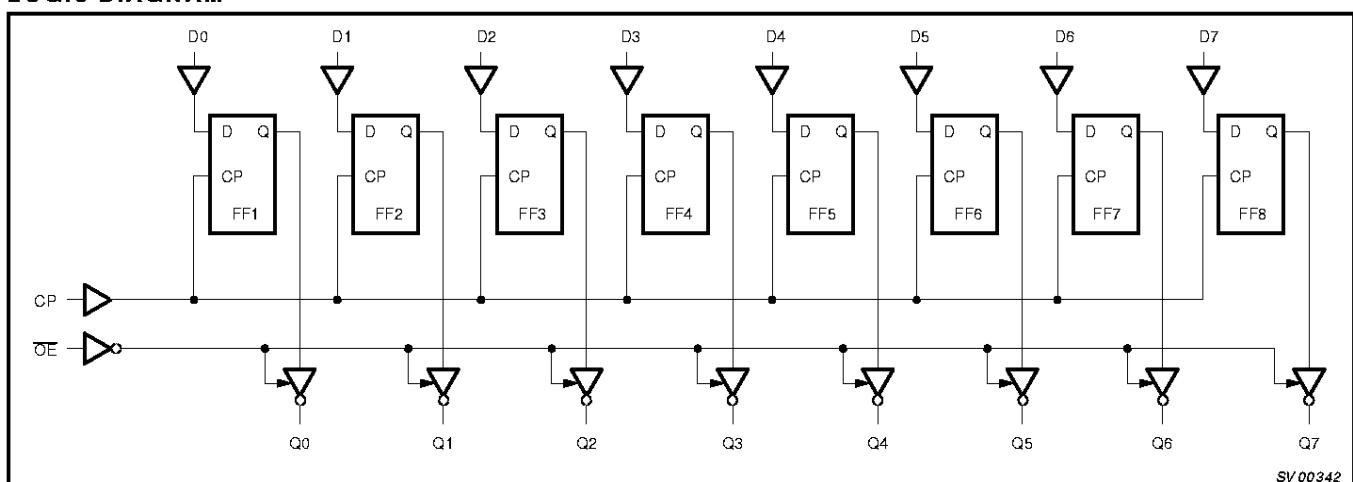
h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition

L = LOW voltage level

I = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition

Z = High impedance OFF-state

↑ = LOW-to-HIGH clock transition

**LOGIC DIAGRAM**

## Octal D-type flip-flop; positive edge-trigger (3-State)

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**RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
$V_{CC}$	DC supply voltage (for max. speed performance)		2.7	3.6	V
$V_{CC}$	DC supply voltage (for low-voltage applications)		1.2	3.6	V
$V_I$	DC input voltage range		0	5.5	V
$V_{I/O}$	DC input voltage range for I/Os		0	$V_{CC}$	V
$V_O$	DC output voltage range		0	$V_{CC}$	V
$T_{amb}$	Operating free-air temperature range		-40	+85	°C
$t_r, t_f$	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0	20 10	ns/V

**ABSOLUTE MAXIMUM RATINGS<sup>1</sup>**

In accordance with the Absolute Maximum Rating System (IEC 134).

Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
$V_{CC}$	DC supply voltage		-0.5 to +6.5	V
$I_{IK}$	DC input diode current	$V_I < 0$	-50	mA
$V_I$	DC input voltage	Note 2	-0.5 to +5.5	V
$V_{I/O}$	DC input voltage range for I/Os		-0.5 to $V_{CC} + 0.5$	V
$I_{OK}$	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	± 50	mA
$V_{OUT}$	DC output voltage	Note 2	-0.5 to $V_{CC} + 0.5$	V
$I_{OUT}$	DC output source or sink current	$V_O = 0$ to $V_{CC}$	± 50	mA
$I_{GND}, I_{CC}$	DC $V_{CC}$ or GND current		± 100	mA
$T_{sig}$	Storage temperature range		-60 to +150	°C
$P_{TOT}$	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

**NOTES:**

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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**DC ELECTRICAL CHARACTERISTICS**

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT	
			Temp = -40°C to +85°C				
			MIN	TYP <sup>1</sup>	MAX		
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V	
		V <sub>CC</sub> = 2.7 to 3.6V	2.0				
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 1.2V			GND	V	
		V <sub>CC</sub> = 2.7 to 3.6V			0.8		
V <sub>OH</sub>	HIGH level output voltage	V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -12mA	V <sub>CC</sub> - 0.5			V	
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -100μA	V <sub>CC</sub> - 0.2	V <sub>CC</sub>			
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -12mA	V <sub>CC</sub> - 0.6				
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -24mA	V <sub>CC</sub> - 1.0				
V <sub>OL</sub>	LOW level output voltage	V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 12mA			0.40	V	
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100μA		GND	0.20		
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 24mA			0.55		
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND	Not for I/O pins		±0.1	±5	μA
I <sub>IHZ</sub> /I <sub>ILZ</sub>	Input current for common I/O pins	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND			±0.1	±15	μA
I <sub>OZ</sub>	3-State output OFF-state current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND			0.1	±10	μA
I <sub>CC</sub>	Quiescent supply current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0			0.1	20	μA
ΔI <sub>CC</sub>	Additional quiescent supply current per input pin	V <sub>CC</sub> = 2.7V to 3.6V; V <sub>I</sub> = V <sub>CC</sub> - 0.6V; I <sub>O</sub> = 0			5	500	μA

**NOTE:**1. All typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.**AC CHARACTERISTICS**GND = 0 V; t<sub>r</sub> = t<sub>f</sub> ≤ 2.5 ns; C<sub>L</sub> = 50 pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS						UNIT		
			V <sub>CC</sub> = 3.3V ±0.3V			V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 1.2V			
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	TYP			
t <sub>PHL</sub> /t <sub>PZH</sub>	Propagation delay CP to Qn	Figures 1, 4	1.5	4.8	8.5	1.5	9.5	21	ns		
t <sub>PZH</sub> /t <sub>PZL</sub>	3-State output enable time OE to Qn	Figures 2, 4	1.5	4.0	7.5	1.5	8.0	17	ns		
t <sub>PHZ</sub> /t <sub>PLZ</sub>	3-State output disable time OE to Qn	Figures 2, 4	1.5	3.5	6.0	1.5	6.5	8.0	ns		
t <sub>w</sub>	Clock pulse width HIGH or LOW	Figure 1	—	3.0	—	—	—	—	ns		
t <sub>su</sub>	Set-up time Dn to CP	Figure 3	—	0.4	—	—	—	—	ns		
t <sub>h</sub>	Hold time Dn to CP	Figure 3	1.0	-0.4	—	1.0	—	—	ns		
f <sub>max</sub>	Maximum clock pulse frequency	Figure 1	75	150					MHz		

**NOTE:**1. These typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.

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**AC WAVEFORMS**

$$V_M = 1.5V \text{ at } V_{CC} \geq 2.7V$$

$$V_M = 0.5V * V_{CC} \text{ at } V_{CC} < 2.7V$$

$V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

$$V_X = V_{OL} + 0.3V \text{ at } V_{CC} \geq 2.7V$$

$$V_X = V_{OL} + 0.1V_{CC} \text{ at } V_{CC} < 2.7V$$

$$V_Y = V_{OH} - 0.3V \text{ at } V_{CC} \geq 2.7V$$

$$V_Y = V_{OH} - 0.1V_{CC} \text{ at } V_{CC} < 2.7V$$

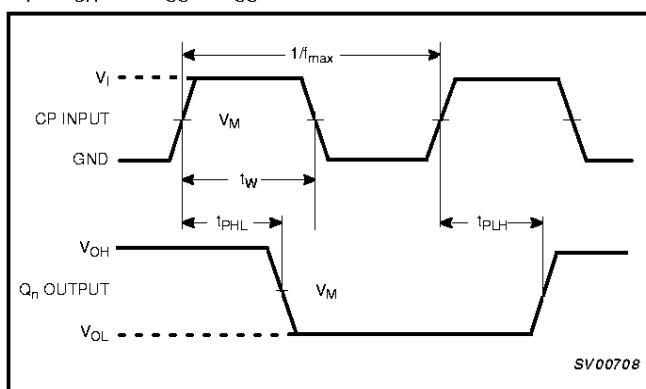


Figure 1. Clock (CP) to output ( $Q_n$ ) propagation delays, the clock pulse width, output transition times and the maximum clock pulse frequency

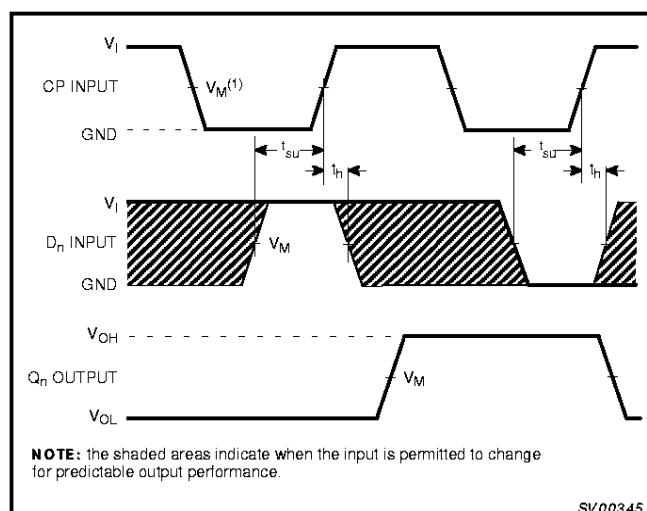


Figure 3. Data set-up and hold times for the  $D_n$  input to the CP input

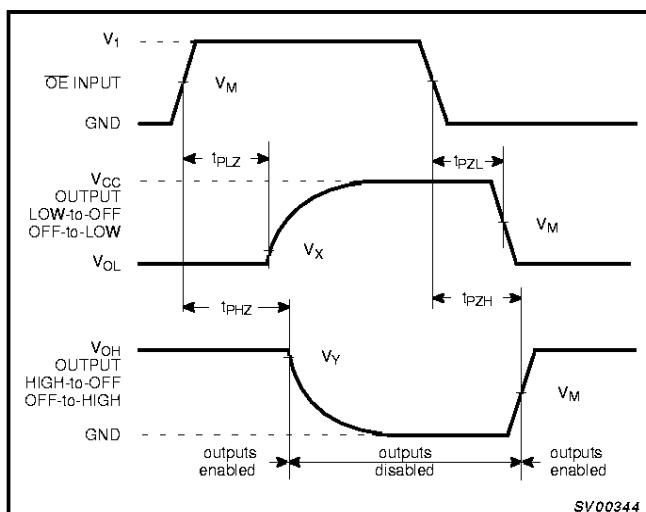
**TEST CIRCUIT**

Figure 2. 3-State enable and disable times

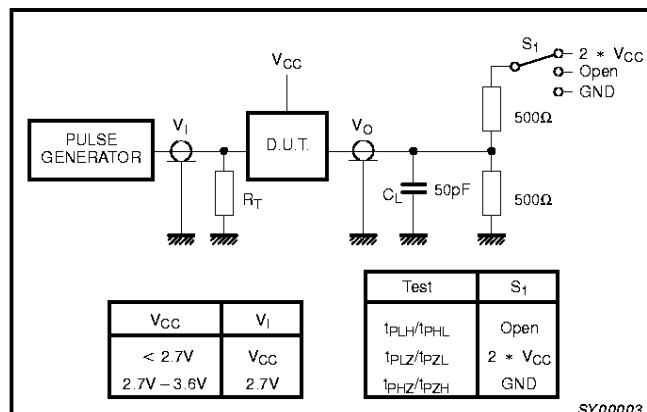


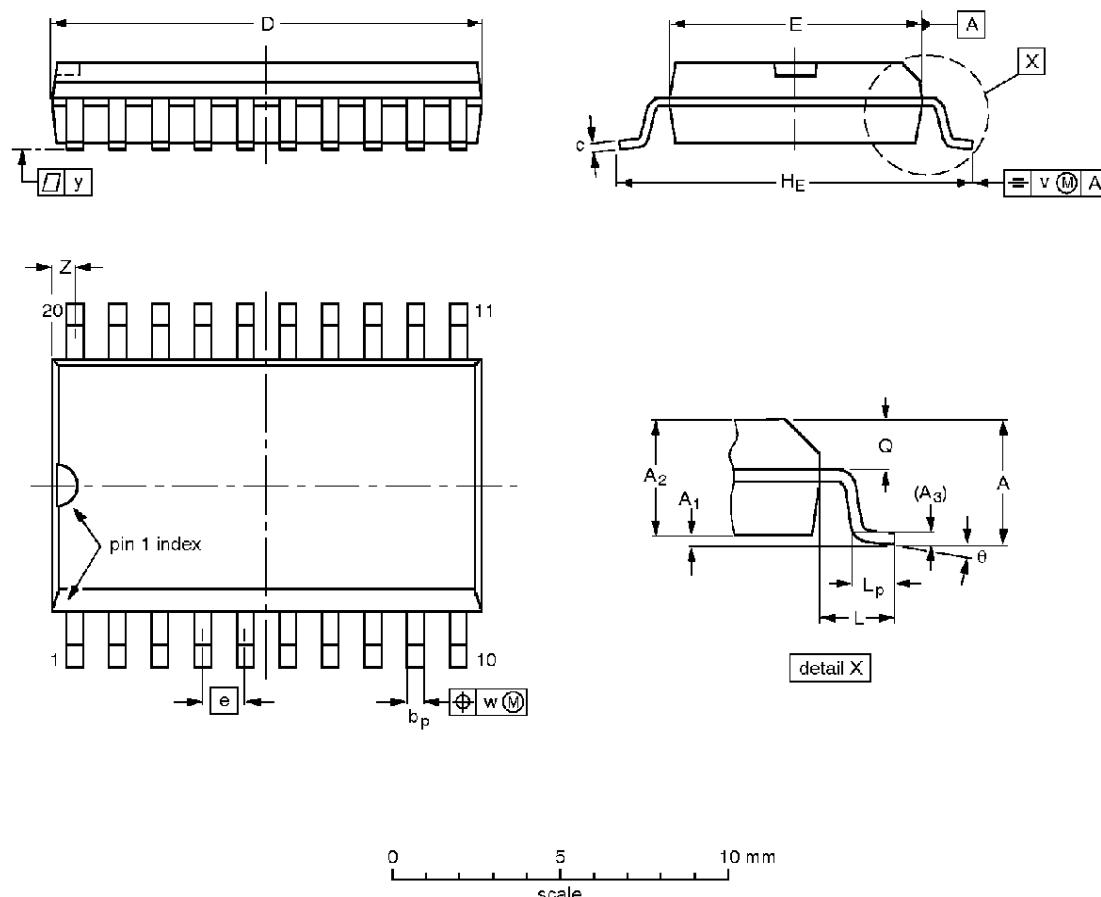
Figure 4. Load circuitry for switching times

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A <sub>max.</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>P</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>P</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.65 0.10	0.30 2.25	2.45	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10 0.004	0.012 0.089	0.096	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

## Note

- Plastic or metal protrusions of 0.15 mm maximum per side are not included.

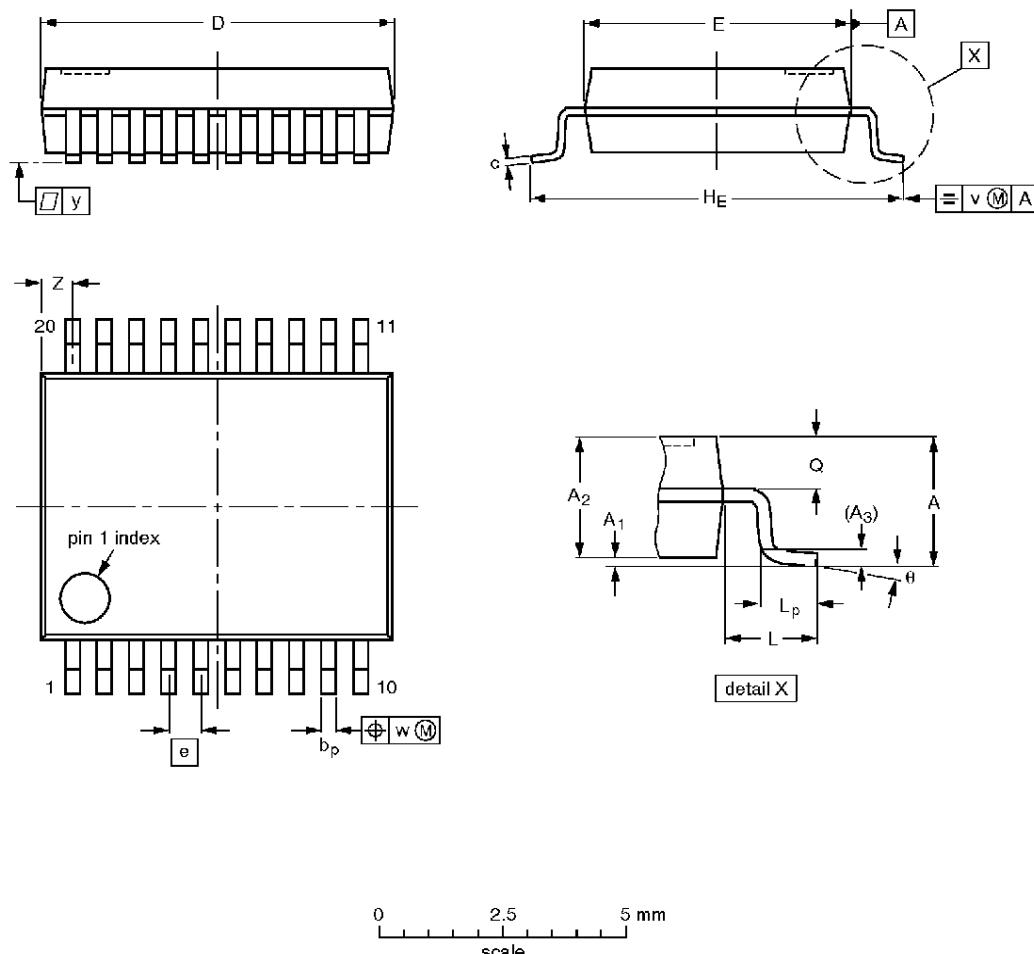
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

## Octal D-type flip-flop; positive edge-trigger (3-State)

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



## DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.0 0.05	0.21 1.65	1.80	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

## Note

- Plastic or metal protrusions of 0.20 mm maximum per side are not included.

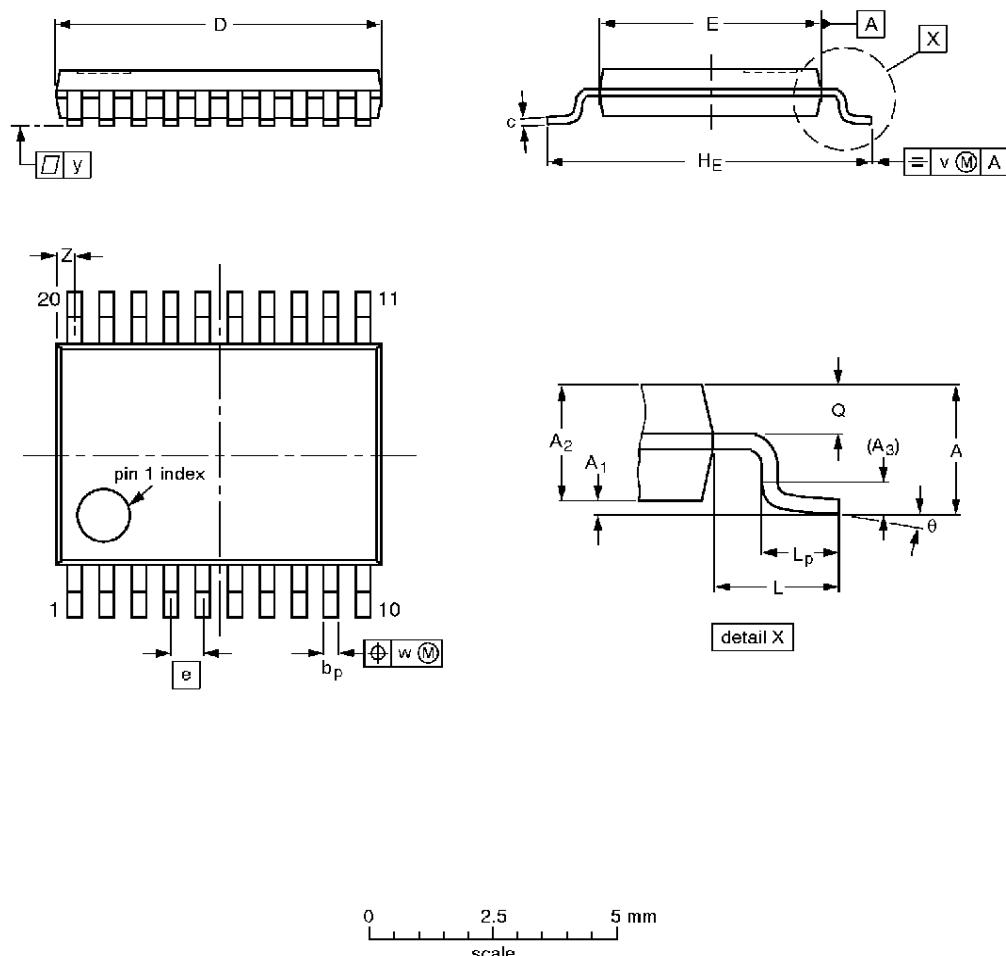
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				-93-09-08- 95-02-04

## Octal D-type flip-flop; positive edge-trigger (3-State)

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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>P</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>P</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.10 0.05	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

## Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				-93-06-16 95-02-04

## Octal D-type flip-flop; positive edge-trigger (3-State)

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**DEFINITIONS**

Data Sheet Identification	Product Status	Definition
<i>Objective Specification</i>	<b>Formative or in Design</b>	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
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